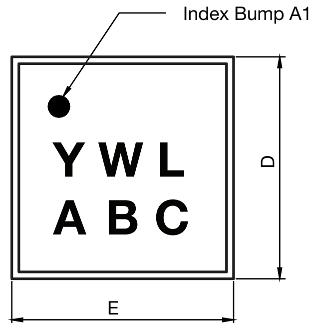
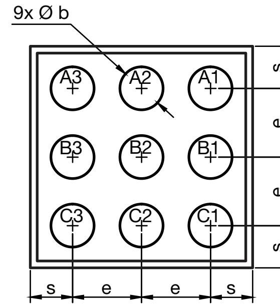
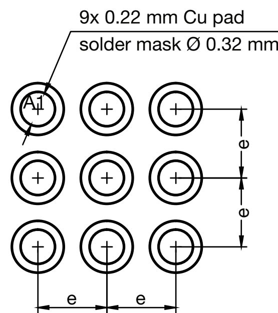
WLCSP9 3 x 3 (9 Bumps) POD (for 17 mil Die thickness)



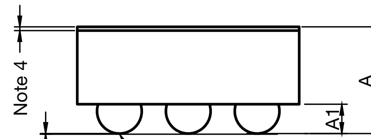
Top View



Bottom View



Recommanded
Land Pattern
(NSMD)



Side View

DIM.	MILLIMETERS			INCHES		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	0.600	0.620	0.640	0.0236	0.0244	0.0252
A1	0.144	0.170	0.196	0.0057	0.0067	0.0077
b	0.220	0.250	0.280	0.0087	0.0098	0.0110
e		0.400			0.0157	
s	0.205	0.225	0.245	0.0081	0.0089	0.0096
D	1.220	1.250	1.280	0.0480	0.0492	0.0504
E	1.220	1.250	1.280	0.0480	0.0492	0.0504

Notes (unless otherwise specified)

1. Laser mark on the silicon die back, coated with an epoxy film.
2. Bumps are SAC396.
3. 0.050 mm max. co-planarity.
4. Laminate tape thickness is 0.022 mm.
5. Use millimeters as the primary measurement

T14-0805-Rev. A, 29-Dec-14 DWG: 6030

For technical questions, contact: powerictechsupport@vishay.com

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